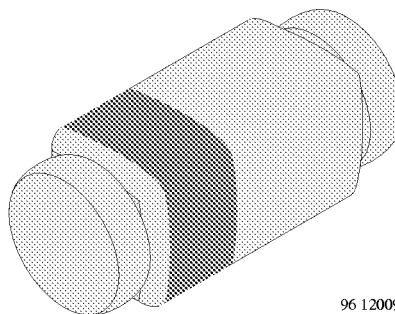


# Schottky Barrier Diode

## Features

- Integrated protection ring against static discharge
- Very low forward voltage



96 12009

## Applications

Applications where a very low forward voltage is required

## Absolute Maximum Ratings

$T_j = 25^\circ\text{C}$

Parameter	Test Conditions	Type	Symbol	Value	Unit
Reverse voltage			$V_R$	50	V
Peak forward surge current	$t_p = 10 \text{ ms}$		$I_{FSM}$	5	A
Repetitive peak forward current	$t_p \leq 1 \text{ s}$		$I_{FRM}$	500	mA
Forward current			$I_F$	200	mA
Average forward current			$I_{FAV}$	200	mA
Junction temperature			$T_j$	125	$^\circ\text{C}$
Storage temperature range			$T_{stg}$	-65...+150	$^\circ\text{C}$

## Maximum Thermal Resistance

$T_j = 25^\circ\text{C}$

Parameter	Test Conditions	Symbol	Value	Unit
Junction ambient	on PC board 50mmx50mmx1.6mm	$R_{thJA}$	320	K/W

## Electrical Characteristics

$T_j = 25^\circ\text{C}$

Parameter	Test Conditions	Type	Symbol	Min	Typ	Max	Unit
Forward voltage	$I_F = 0.1 \text{ mA}$		$V_F$			300	mV
	$I_F = 1 \text{ mA}$		$V_F$			380	mV
	$I_F = 10 \text{ mA}$		$V_F$			450	mV
	$I_F = 30 \text{ mA}$		$V_F$			600	mV
	$I_F = 100 \text{ mA}$		$V_F$			900	mV
Reverse current	$V_R = 40 \text{ V}$		$I_R$			5	$\mu\text{A}$
Diode capacitance	$V_R = 1 \text{ V}, f = 1 \text{ MHz}$		$C_D$			8	pF

### Characteristics ( $T_j = 25^\circ\text{C}$ unless otherwise specified)

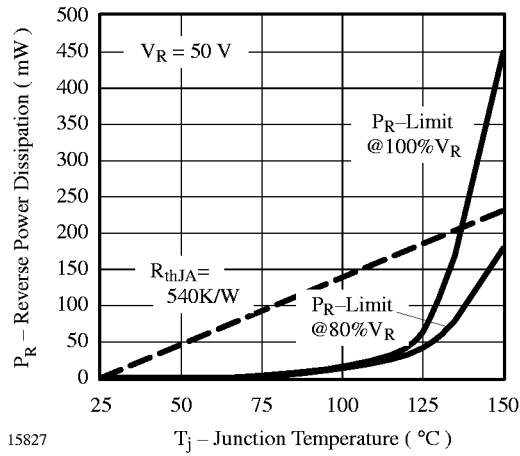


Figure 1. Max. Reverse Power Dissipation vs. Junction Temperature

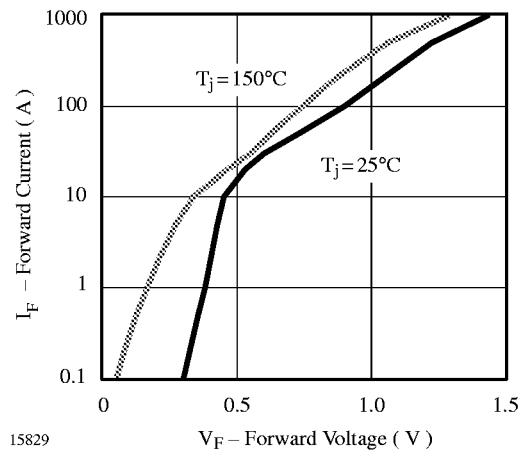


Figure 3. Forward Current vs. Forward Voltage

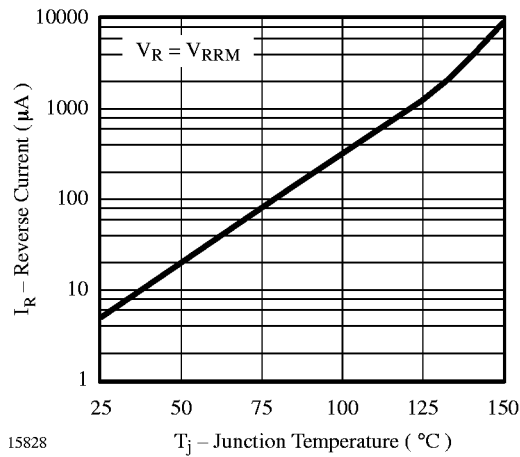


Figure 2. Reverse Current vs. Junction Temperature

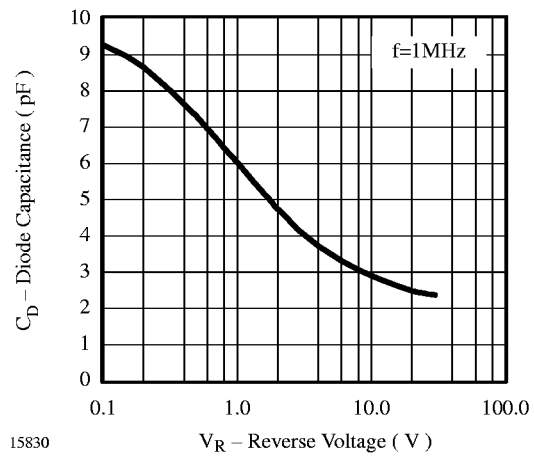
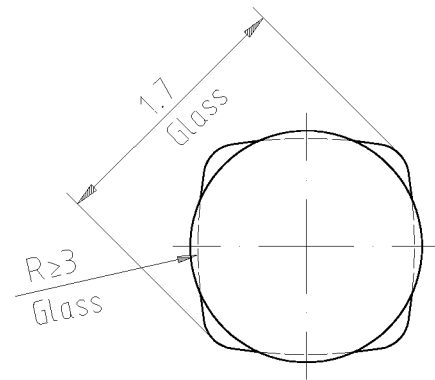
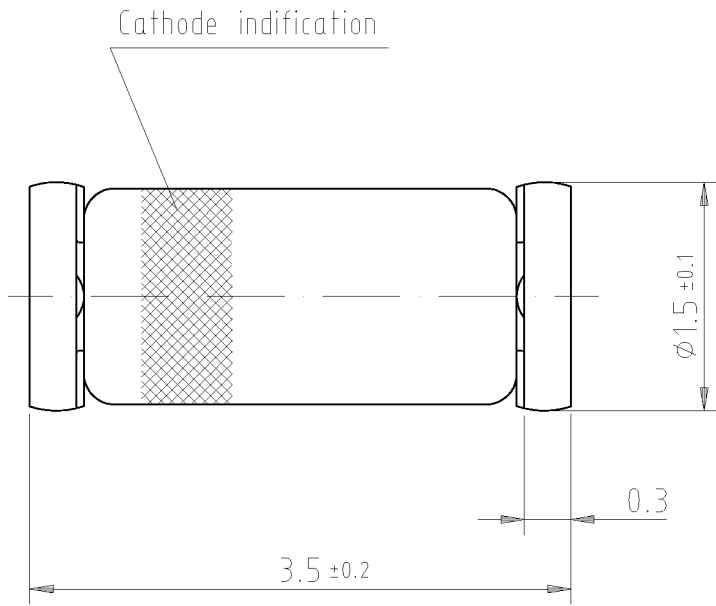
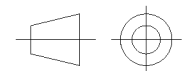


Figure 4. Diode Capacitance vs. Reverse Voltage

**Dimensions in mm**



Glass case  
Quadro MELF  
similar to JEDEC 213 AA



technical drawings  
according to DIN  
specifications

96 12071